Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (*Canceled*)

2. (*Currently Amended*) A method for producing, on a substrate, an electronic component with closely adjacent electrodes, the method comprising:

depositing a first metal layer onto the substrate;

structuring a first photo lacquer on a surface of the first metal layer, wherein a portion of the surface of the first metal layer does not have the first photo lacquer thereon;

etching the portion of the surface of the first metal layer not having the first photo lacquer;

undercut etching the first metal layer so that an overhang is defined by the first photo lacquer;

exposing, to a metal vapor, a surface of the first photo lacquer and an exposed portion of the substrate where the first metal layer was etched away so that a second metal layer is formed on the surface of the first photo lacquer and the exposed portion of the substrate where the first metal layer was etched away except in a space between the overhang and the substrate; [[and]]

removing ~~both the first photo lacquer and~~ the second metal layer from the surface of the first photo ~~lacquer.~~ lacquer and removing the first photo lacquer;

etching a hole into the substrate at a position other than a position of the first metal layer and the second metal layer;

depositing a third metal layer onto the substrate, the first metal layer, and the second metal layer;

applying an insulator onto the third metal layer;

applying an organic semiconductor onto the third metal layer and the insulator; and

applying a sealing layer onto the organic semiconductor.

3-12. (*Canceled*)

13. (*Currently Amended*) The method of claim [[4]] 2, further ~~comprising~~ comprising:

making the third metal layer from gold.

14-18. (*Canceled*)

19. (*Currently Amended*) An electronic component with closely adjacent electrodes, comprising:

a substrate;

a first electrode on the substrate, wherein the first electrode has a first thickness;

a second electrode on the substrate, wherein the second electrode has a second thickness, and wherein a separation between the first electrode and the second electrode is about ten nanometers;

a third electrode in a hole in the substrate, wherein the third electrode has a third thickness, and wherein the third electrode is positioned within the separation between the first electrode and the second electrode;

an insulator on the third electrode;

an organic semiconductor on the first electrode, the second electrode, and the insulator; and

a sealing layer on the organic ~~semiconductor.~~ semiconductor;

wherein the first and second thicknesses are at least approximately twice the third thickness.

20. (*Previously Presented*) The electronic component of claim 19, wherein the substrate comprises either a polymer film or a glass other than SiO_2.

21. (*Previously Presented*) The electronic component of claim 19, wherein the first electrode comprises either chromium or gold.

22. (*Previously Presented*) The electronic component of claim 19, wherein the third electrode comprises gold.

23. (*Currently Amended*) A device, comprising:

a first electrode on a substrate, wherein the first electrode has a first thickness, and wherein the substrate includes ~~comprising~~ a glass other than SiO_2;

a second electrode on the substrate, wherein the second electrode has a second thickness and is separated about ten nanometers from the first electrode;

a third electrode in a hole in the substrate, wherein the third electrode has a third thickness and ~~wherein the third electrode~~ is positioned between the first electrode and the second electrode;

an insulator on the third electrode;

a semiconductor on the first electrode, the second electrode, and the insulator; and

a sealing layer on the ~~semiconductor.~~ semiconductor;

wherein the first and second thicknesses are at least approximately twice the third thickness.

24. (*Currently Amended*) The ~~electronic component~~ device of claim 23, wherein the first electrode comprises either chromium or gold.

25. (*Currently Amended*) The ~~electronic component~~ device of claim 23, wherein the third electrode comprises gold.

26. (*Previously Presented*) The method of claim 2, wherein said structuring comprises structuring the first photo lacquer on the surface of the first metal layer so that the first photo lacquer is in direct physical contact with the surface of the first metal layer.

27. (*Previously Presented*) The electronic component of claim 19, wherein the first electrode and the second electrode are produced by:

forming a first metal layer on the substrate;

forming a photo lacquer on a first portion of the first metal layer;

etching a second portion of the first metal layer to expose a first portion of the substrate;

undercut etching the first metal layer to expose a second portion of the substrate so that an overhang is defined by the photo lacquer;

forming a second metal layer on the first portion of the substrate so that a space is defined between the overhang and the second portion of the substrate; and

removing the photo lacquer so that the first electrode comprises the first portion of the first metal layer and the second electrode comprises the second metal layer.

28. (*Previously Presented*) The device of claim 23, wherein the first electrode and the second electrode are produced by:

forming a first metal layer on the substrate;

forming a photo lacquer on a first portion of the first metal layer;

etching a second portion of the first metal layer to expose a first portion of the substrate;

undercut etching the first metal layer to expose a second portion of the substrate so that an overhang is defined by the photo lacquer;

forming a second metal layer on the first portion of the substrate so that a space is defined between the overhang and the second portion of the substrate; and

removing the photo lacquer so that the first electrode comprises the first portion of the first metal layer and the second electrode comprises the second metal layer.